Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 5800-24G-SFP Switch w 1 Intf Slt(JC103B)
HP 5800AF-48G Switch(JG225B)
HP 5800-24G-SFP TAA Switch w 1 Intf Slt(JG256B)
HP A5800-24G-SFP Switch with 1 Interface Slot （JC103A）
HP A5800-48G Switch （ JG225A）
HP A5800-24G-SFP TAA-compliant Switch with 1 Interface Slot （JG256A）

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on power module 2,and then remove power module 2 .
3. Unscrew the screws on fan-assembly 3, and then remove fan-assembly 3.
4. Unscrew the screws on filler panel 4, and then remove filler panel 4.
5. Remove AC cable holder 5.
6. Unscrew the screws on top 12, and then remove top 12 from the enclosure.
7. Unscrew the screws on PCB 8, and then remove PCB 8 from the enclosure.
8. Unscrew the screws on PCB 14, and then remove PCB 14 from the enclosure.
9. Unscrew the screws on radiator13, and then removeradiato13 from the enclosure.
10. Unscrew the screws on part 9, and then removepart 9 from the enclosure.
11. Unscrew the screws on PCB 8, and then remove PCB 8 from the enclosure.
12. Unscrew the screws on PCB 10, and then remove PCB 10 from the card.
13. Unscrew the screws on PCB10, and remove the front panel11 from the card.
14. Remove front panel set 15 from base 7.
15. Unscrew the screws on plastic fender 16, and remove plastic fender 16 from mother PCB 6.
16. Unscrew the screws on mother PCB 6, and then remove mother PCB 6 from the enclosure.
17. Remove all of the labels.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

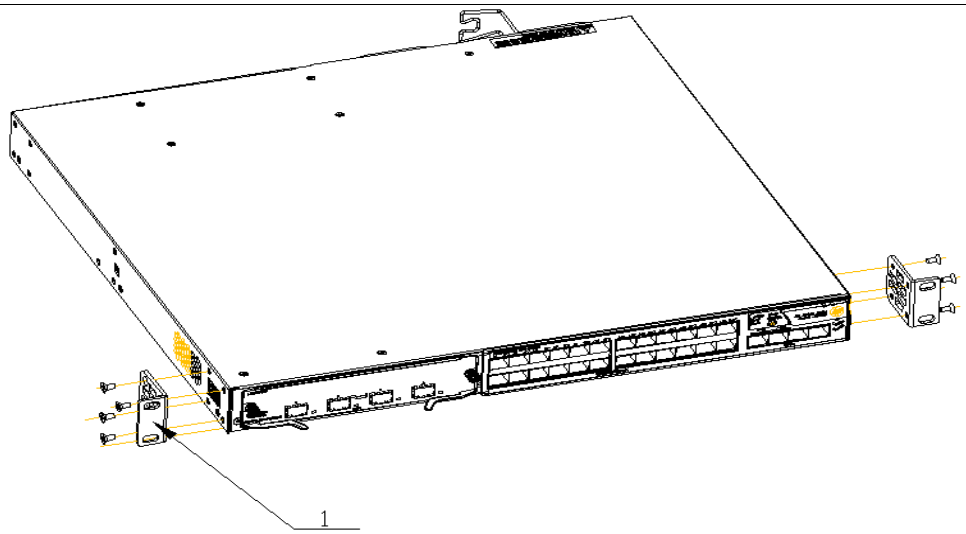

Figure 1Remove mounting angle

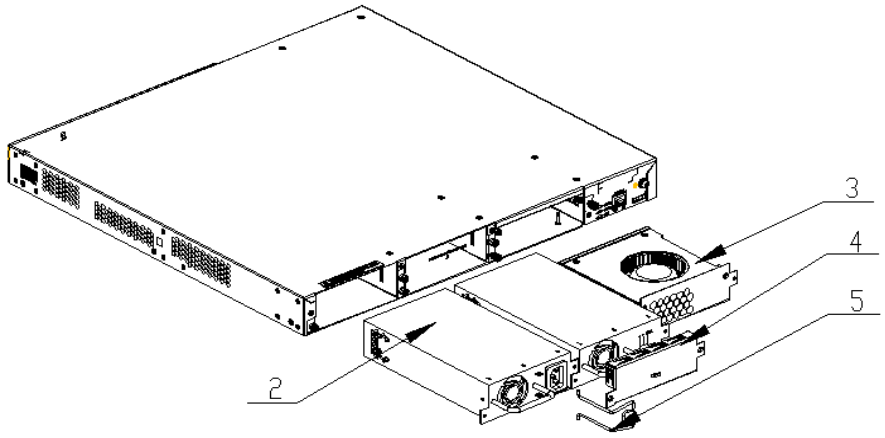

Figure 2 Treatment to the product（I）

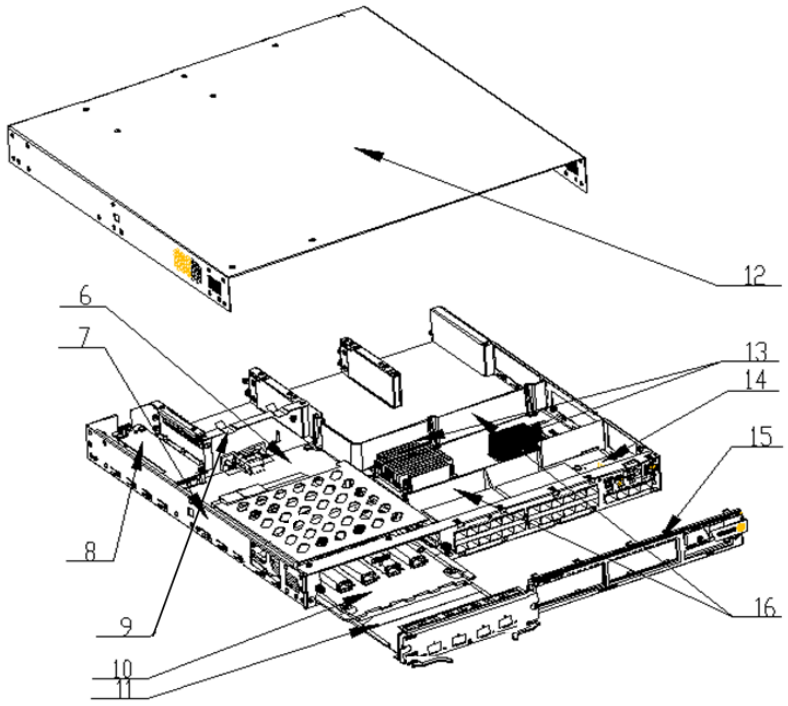

Figure 3 Treatment to the product（II）

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	78	1.0%		Fe recycling
2		Complex PCB	940	12.2%	The surface of PCB is greater than 10 square centimeters;	
3		PC	460	6.0%		PC recycling
4		Fe	50	0.7%		Fe recycling
5		Fe	4	0.1%		Fe recycling
6		Complex PCB	1100	14.3%	The surface of PCB is greater than 10 square centimeters;	
7		Fe	2341	30.5%		Fe recycling
8		Complex PCB	30	0.4%	The surface of PCB is greater than 10 square centimeters;	
9		Fe	15	0.2%		Fe recycling
10		Complex PCB	340	4.4%	The surface of PCB is greater than 10 square centimeters;	
11		Fe	373	4.9%		Fe recycling
12		Fe	1830	23.8%		Fe recycling
13		Al	27	0.4%		Al recycling
14		Complex PCB	30	0.4%	The surface of PCB is greater than 10 square centimeters;	
15		PC	19	0.2%		PC recycling
16		PC	45	0.6%		PC recycling

4.0 Revised record

Date	Version	Author	Modify content
2014.11.20	V0	Wu Xuejun	Initial version